



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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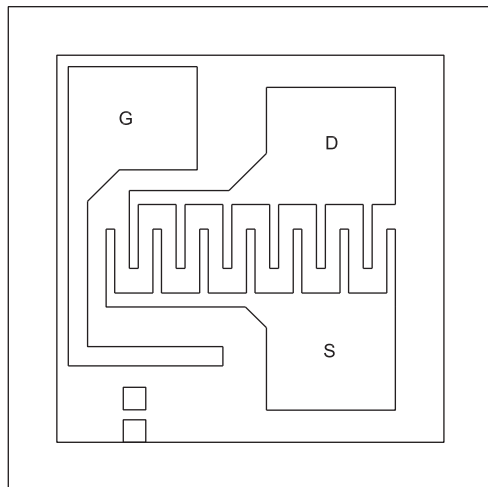
**PROCESS CP210**  
**Small Signal Transistors**  
N - Channel Silicon Amplifier J FET Chip



**PROCESS DETAILS**

Process	EPITAXIAL PLANAR
Die Size	15 x 15 MILS
Die Thickness	8.0 MILS
Drain Bonding Pad Area	3.2 x 4.0 MILS
Source Bonding Pad Area	3.2 x 4.0 MILS
Gate Bonding Pad Area	3.2 x 4.0 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 6,000Å

**GEOMETRY**



BACKSIDE GATE R1

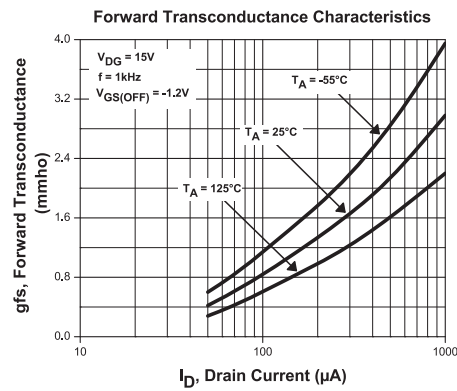
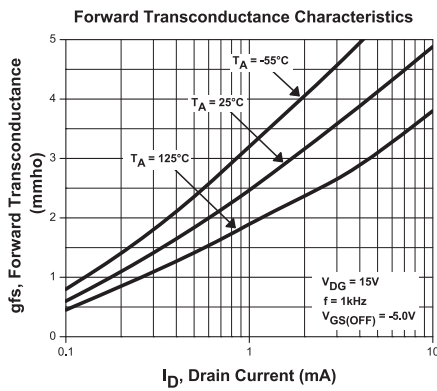
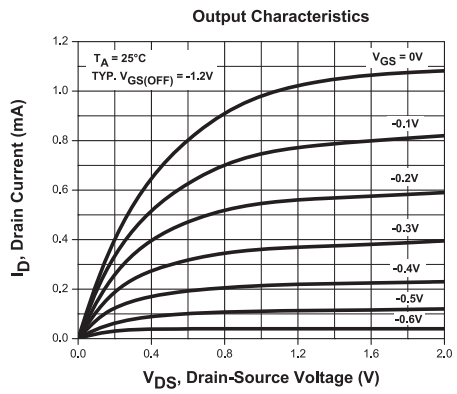
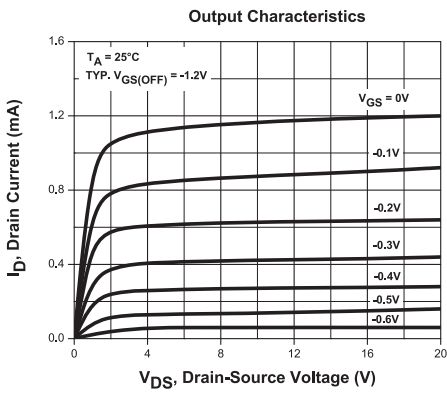
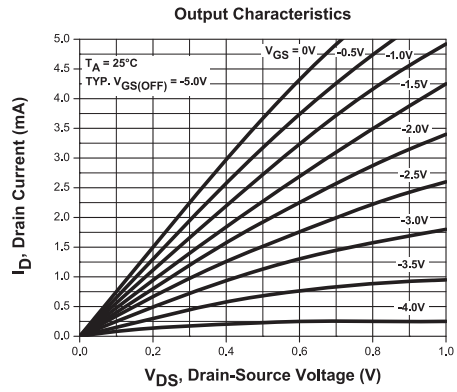
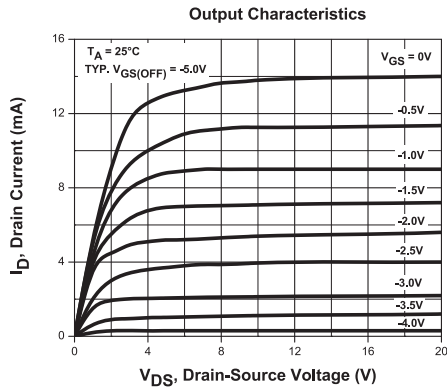
**GROSS DIE PER 4 INCH WAFER**  
53,730

**PRINCIPAL DEVICE TYPES**  
2N4416A  
CMPF4416A

R5 (22-March 2010)

# PROCESS CP210

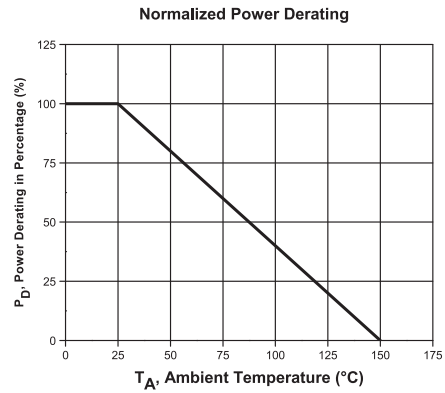
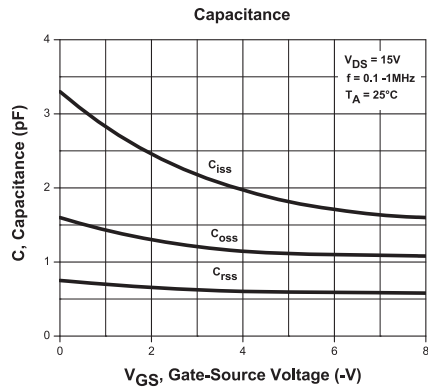
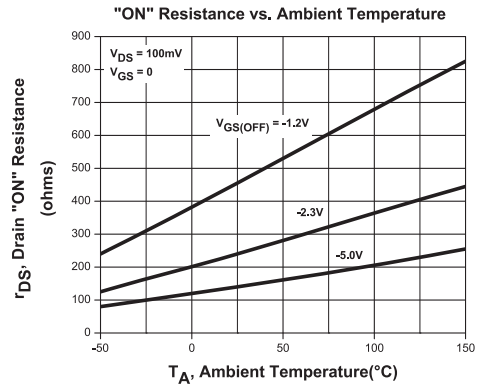
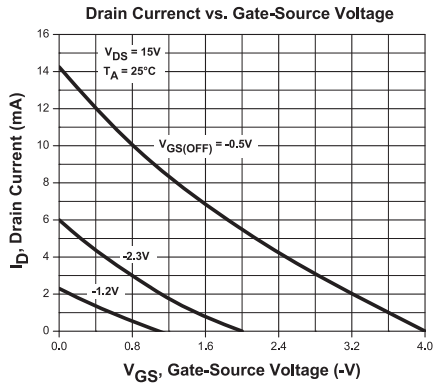
## Typical Electrical Characteristics



R5 (22-March 2010)

# PROCESS CP210

## Typical Electrical Characteristics



R5 (22-March 2010)